

Agency Recognitions

Agency	Agency File Number
<i>21</i> 7	E128662

Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 125	°C
Current Rating ¹	I _{PP}	6	kA

1. Rated I_{DD} measured with 8/20µs pulse

Description

The AK6-Y series of high power TVS diode is specially designed for meeting severe surge test environment of both AC and DC line protection applications. It features a very fast response and ultra low clamping characteristics as compared to MOVs (Metal Oxide Varistors). It accomplishes this by virtue of the Littelfuse $Foldback^{\text{TM}}\ technology, which\ provides\ a\ clamping\ voltage\ lower$ than the avalanche voltage (but above the rated working voltage); therefore, any voltage rise due to increased current conduction is maintained at a minimum magnitude, providing the best possible protection level. These AK components can be connected in series and / or parallel to create a very high surge current protection solution.

Features & Benefits

- Recognized to UL 497B as an Isolated Loop Circuit Protector
- Both reflow and wave soldering capable
- Very low clamping voltage
- Ultra compact: less than onetenth the size of traditional discrete solutions
- Sharp breakdown voltage
- Low slope resistance
- Bi-directional
- Foldback technology for superior clamping factor
- Symmetric in leads width for easier soldering during assembly.

- IEC-61000-4-2 ESD 15kV(Air), 8kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2
- EFT protection of data lines in accordance with IEC 61000-
- Halogen-free and RoHS compliant
- Glass passivated junction
- Pb-free E4 means 2nd level interconnect is Pb-free and the terminal finish material is silver

Functional Diagram



Electrical Characteristics (T_A=25°C unless otherwise noted)

Part Numbers	Part Marking	Standoff Voltage (V _{so}) Volts	Max. Reverse Leakage (I _R) @V _{SO}	Typical I _R @ 85°C (μΑ)		Breakdown (V _{BR}) @ I _T	Test Current I _T	V _{CL} @ I _{pp}	ping Voltage Peak Pulse _{PP}) (Note 1)	Max. Temp Coefficient OF V _{BR}	Max. Capacitance 0 Bias 10kHz	Agency Approval
		(V _{SO}) VOILS	μA	(μ.Α.)	Min Volts	Max Volts	(mA)	V _{CL} Volts	I _{PP} Amps	(%/°C)	(nF)	<i>71</i>
AK6-030C-Y	6-030C	30	10	15	32	37	10	90	6,000	0.1	11.0	X
AK6-058C-Y	6-058C	58	10	15	64	70	10	110	6,000	0.1	8.0	Χ
AK6-066C-Y	6-066C	66	10	15	72	80	10	120	6,000	0.1	6.0	Χ
AK6-076C-Y	6-076C	76	10	15	85	95	10	140	6,000	0.1	6.5	Χ
AK6-170C-Y	6-170C	170	10	15	180	220	10	260	6,000	0.1	2.8	Χ
AK6-190C-Y	6-190C	190	10	15	200	245	10	290	6,000	0.1	2.5	Χ
AK6-240C-Y	6-240C	240	10	15	250	285	10	340	6,000	0.1	2.0	X
AK6-270C-Y	6-270C	270	10	15	280	320	10	380	6,000	0.1	1.6	X
AK6-380C-Y	6-380C	380	10	15	401	443	10	520	6,000	0.1	1.4	X
AK6-430C-Y	6-430C	430	10	15	440	490	10	625	6,000	0.1	1.0	X

Note: Using 8/20µs wave shape as defined in IEC 61000-4-5.



Figure 1 - Peak Power Derating

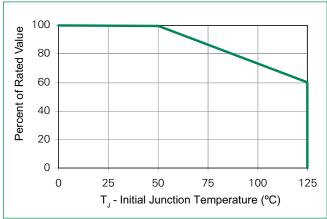


Figure 3 - Typical Peak Pulse Power Rating Curve

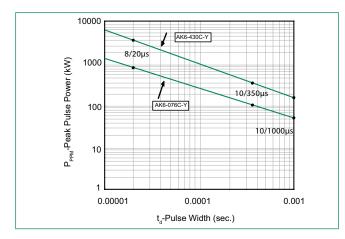
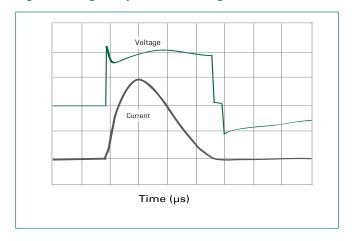


Figure 5 -Surge Response (8/20 Surge current waveform)





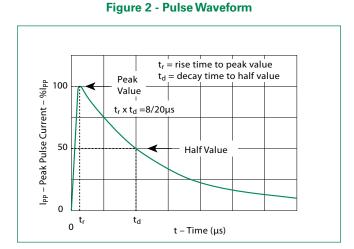
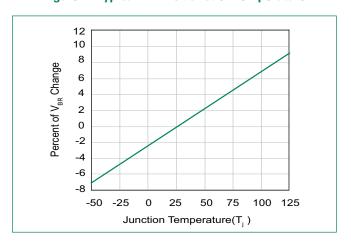


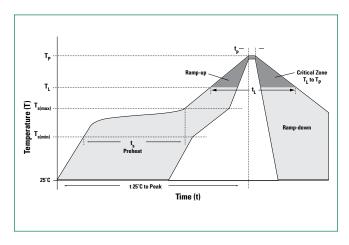
Figure 4 - Typical VBR Vs Junction Temperature





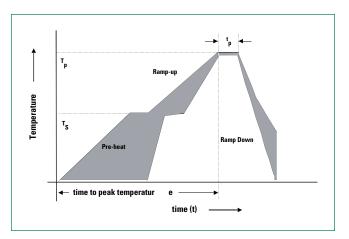
Soldering Parameters

Reflow Cond	dition	Lead-free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (min to max) (t _s)	60 - 120 secs	
Average ram peak	p up rate (Liquidus Temp (T _L) to	3°C/second max	
$T_{\text{S(max)}}$ to T_{A} -	Ramp-up Rate	3°C/second max	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
nellow	-Time (min to max) (T _s)	60 – 150 seconds	
Peak Temper	rature (T _P)	260 ^{+0/-5} °C	
Time within	5°C of actual peak Temperature (t _p)	30 seconds	
Ramp-down	Rate	6°C/second max	
Time 25°C to	peak Temperature (T _p)	8 minutes Max.	
Do not exce	ed	260°C	



Flow Soldering (Solder Dipping)

Reflow Cond	dition	Lead-free assembly
Pre Heat	- Temperature Min (T _{s(min)})	140°C
	-Temperature Max (T _{s(max)})	160°C
	- Time to Pre-Heat Temp	60 - 150 secs
Average ram	np up rate to Pre-Heat Temp	5°C/second max
Peak Temper	rature (T _P)	260+0/-5 °C
Average ram	np up rate (pre-heat to T _p)	5°C/second max
Time within	actual peak Temperature Max	6 seconds
Ramp-down	Rate	5°C/second max

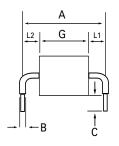


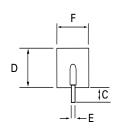
Physical Specifications

Weight	Contact manufacturer
Case	UL Recognized compound meeting flammability rating V-0
Terminal	Silver plated leads, solderable per MIL-STD-750 Method 2026



AK6-Y Series Axial Leaded – 6kA

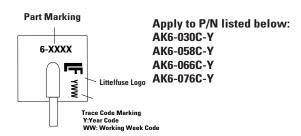




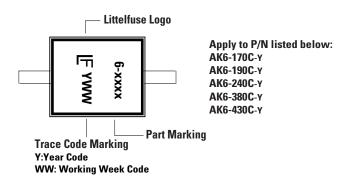
Dimensions

Dimensions	Inches	Millimeters	
А	0.950 +/- 0.040	24.15 +/- 1.00	
В	0.095 +/- 0.024	2.4 +/- 0.60	
С	0.236 +/- 0.040	6.00 +/- 1.00	
D	0.570 max.	14.48 max.	
Е	0.050 +/- 0.002	1.270 +/- 0.05	
F	0.500 max.	12.70 max.	
G - 030C-Y	0.161 +/- 0.040	4.10 +/- 1.00	
G - 058C-Y/066C-Y 076C-Y	0.189 +/- 0.040	4.8 +/- 1.00	
G - 170C-Y/190C-Y	0.320 +/- 0.040	8.13 +/- 1.00	
G - 240C-Y	0.370 +/- 0.040	9.4 +/- 1.00	
G - 380C-Y/430C-Y	0.543 +/- 0.040	13.8 +/- 1.00	
L1/L2	L1= L2 tolerance +/	'- 0.04 inch (1.0 mm)	

Part Marking System

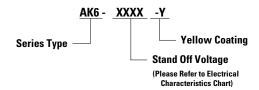


Type 1- Side View



Type 2 - Top View

Part Numbering System



Packing Options

Part Number	Component Package	Quantity	Packaging Option
AK6-XXXX-Y	AK Package	56pcs/Box	Bulk
AK6-XXXX-Y-12	AK Package	12pcs/Box	Bulk

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